

Abstract

The invention relates to a method of gluing substrates which are hydrophobic and oleophobic as a result of having been treated earlier using a fluorinated compound, said substrates being intended for packaging. The inventive method comprises applying an adhesive to at least one of the substrates, said adhesive comprising: a) 5 to 50 weight percent of at least one styrenic block copolymer (preferably, 15 to 30%); b) 20 to 60 weight percent of at least one tackifying resin which is compatible with the non-styrene phase (preferably, 35 to 55%); c) 0 to 20 weight percent of at least one tackifying resin which is compatible with the styrene phase and, (preferably, 5 to 15%); d) 5 to 25 weight percent of at least one thermofusible wax (preferably, 10 to 17%); e) 3 to 20 weight percent of liquid plasticizers which are normally used in thermofusible adhesives; and/or f) additives. In this way, said mixture presents the following characteristics: (i) a viscosity of between 400 and 3000 mPa·s at 170°C (preferably, between 700 and 1400 mPa·s); and (ii) a softening point included between 75 and 120°C.